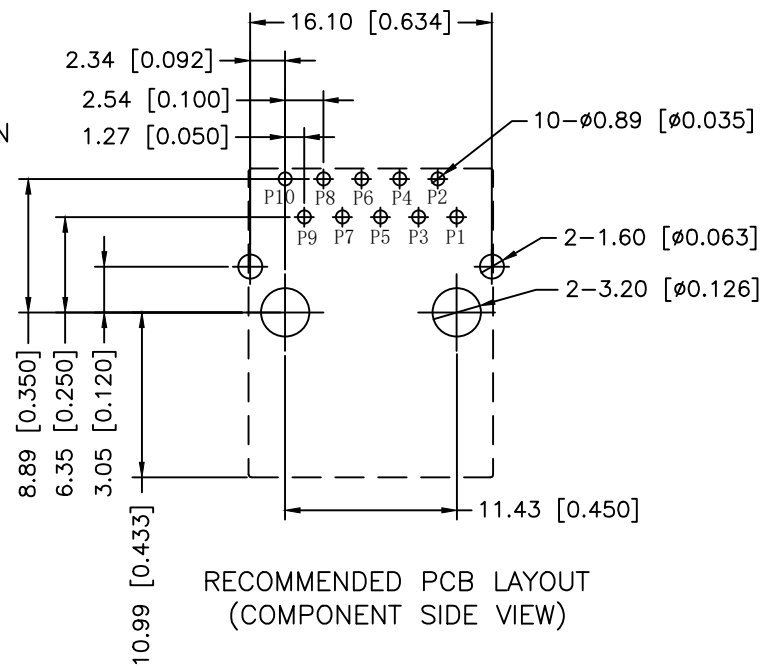
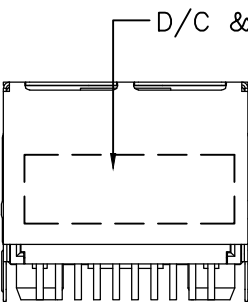
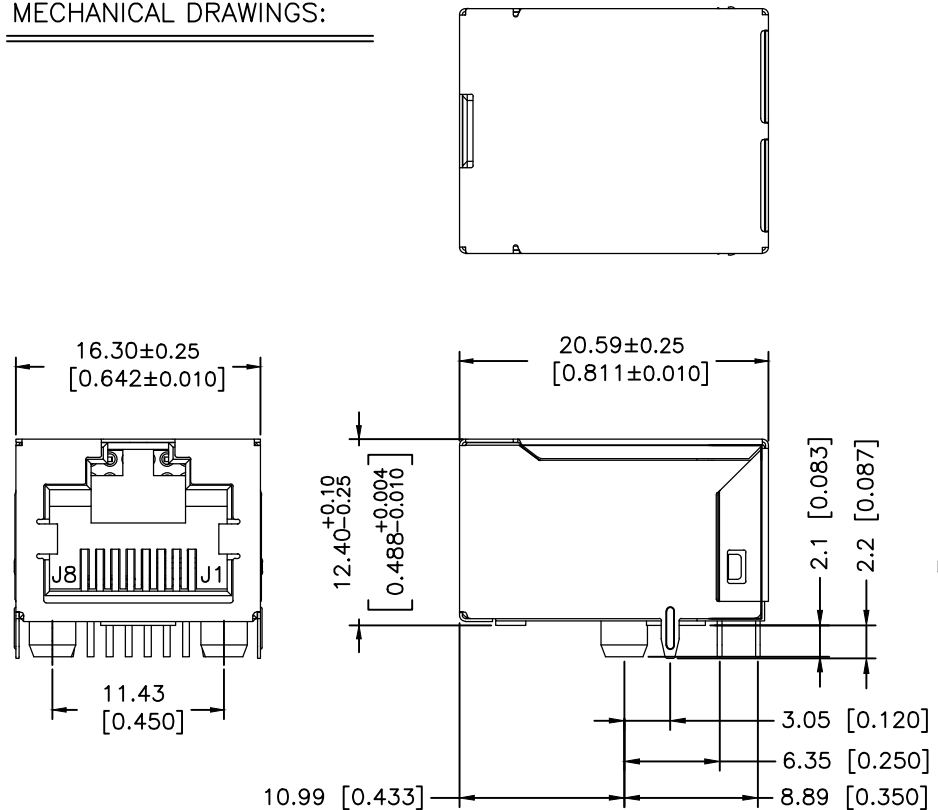
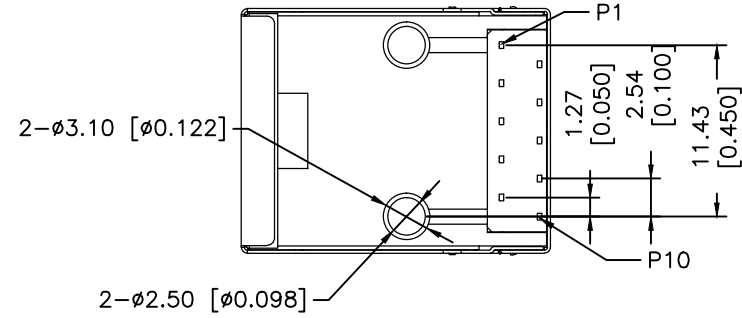


MECHANICAL DRAWINGS:

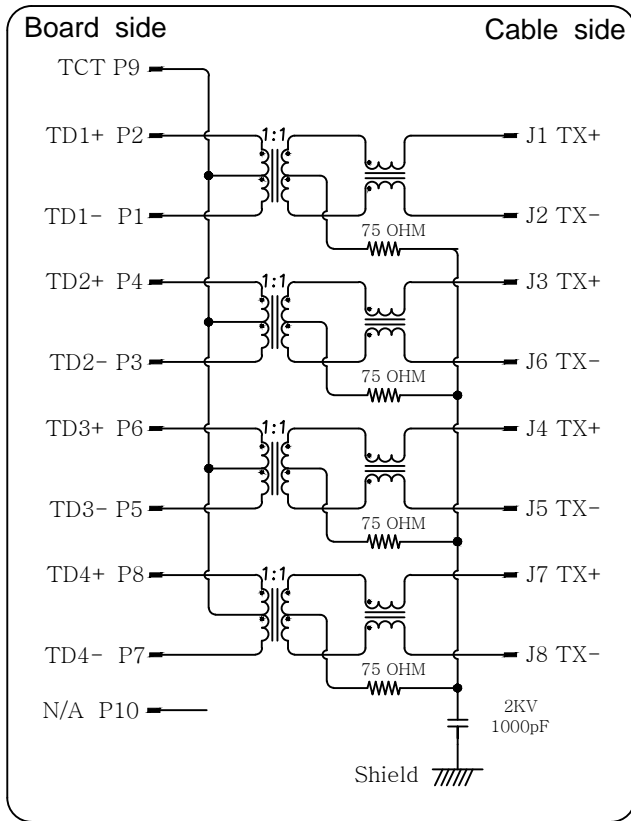


RECOMMENDED PCB LAYOUT
(COMPONENT SIDE VIEW)






QUALITY SYMBOLS MAJOR CRITICAL	DRAWN BY DENG JIANXIANG '180516 DATE	
	CHECKED BY TENG CHANG HO '180516 DATE	
GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±XXX .X ±0.38 .XX ±0.20 .XXX ±XXX ANGLES ±1°	APPROVED BY KUO JUNG HSUN '180516 DATE	DWG NO. 30836-XXXXXXX-XXX
UNITS mm		SIZE A4
SCALE 1:1	SHEET NO. 1 OF 3	REV 1
		PART NO. SEE NOTES

SCHEMATIC FOR RJ45:



ELECTRICAL CHARACTERISTICS :

1. INSERTION LOSS :
 - 1~100 MHz -1.0dB MAX.
2. RETURN LOSS(LOAD 100Ω) :
 - 1~30 MHz -18dB MIN
 - 30~60 MHz -16dB MIN
 - 60~80 MHz -12dB MIN
 - 80~100 MHz -10dB MIN
3. COMMON MODE REJECTION
 - 1~100 MHz -30dB MIN
4. CROSS TALK
 - 1~100 MHz -30dB MIN
5. INDUCTANCE @ 100KHz, 0.1V, 8mA DC BIAS
 - (P2-P1),(P4-P3),(P6-P5),(P8-P7) : 350 uH MIN
6. DCR
 - (J1-J2),(J3-J6),(J4-J5),(J7-J8) : 1.2 Ohm MAX
7. HI-POT TEST
 - PCB SIDE TO CABLE SIDE :
1500VAC 60S OR 2250VDC 60S
8. TURNS RATION 100KHz
 - (P2-P1) : (J1-J2) = 1:1 ±%5
 - (P4-P3) : (J3-J6) = 1:1 ±%5
 - (P6-P5) : (J4-J5) = 1:1 ±%5
 - (P8-P7) : (J7-J8) = 1:1 ±%5

QUALITY SYMBOLS MAJOR  CRITICAL 	DRAWN BY	DATE	
	DENG JIANXIANG	'180516	
GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±XXX .X ±0.38 .XX ±0.20 .XXX ±XXX ANGLES ±1°	CHECKED BY	DATE	TITLE
	TENG CHANG HO	'180516	
	APPROVED BY	DATE	UNITS
KUO JUNG HSUN	'180516	mm	A4
		SCALE	DWG. NO.
		1:1	30836-XXXXXXXX-XXX
		SHEET NO.	PART NO.
		2 OF 3	SEE NOTES
		REV	
		1	

SPECIFICATIONS :

1. MATERIAL

- HOUSING : HIGH TEMPERATURE THERMOPLASTIC, PA9T(YELLOW PANTONE 128C), UL 94V-0, ,HSF
- MODULE CASE : HIGH TEMPERATURE THERMOPLASTIC, LCP, UL 94V-0, BLACK,HSF
- RJ CONTACTS : PHOSPHOR BRONZE, C5210R-H
PLATING : 30u" GOLD ON CONTACT AREA,
100u" MIN TIN PLATING ON SOLDER TAILS,
OVER 50~100u" NICKEL OVERALL
- SOLDER TAIL TERMINAL : BRASS, C2680R-EH
PLATING : 100u" TIN MIN OVER 50u" NICKEL OVERALL
- SHIELD : STAINLESS, SUS304-1/2H,THICKNESS=0.2MM, PRE-SOLDERING

2. ELECTRICAL

- INSULATION RESISTANCE : 500 MOHMS MIN
- DIELECTRIC WITHSTANDING VOLTAGE : 1000 VAC FOR 1 MINUTE

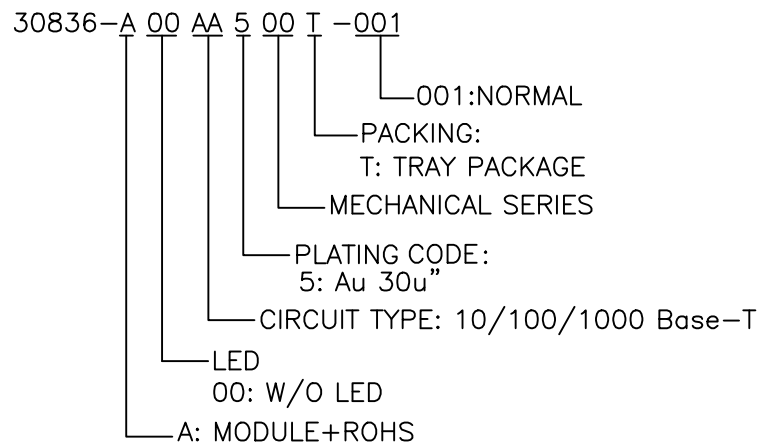
3. DURABILITY TEST RATING

- INSERTION FORCE WITH THE LATCH DEPRESSED :22N MAX
- REMOVAL FORCE WITH THE LATCH DEPRESSED :44N MAX
- DURABILITY :750 CYCLES

4. OPERATING AND STORAGE TEMPERATURE

- OPERATING TEMPERATURE : 0°C TO +70°C
- STORAGE TEMPERATURE : -40°C TO +85°C

P/N RULE CODE:

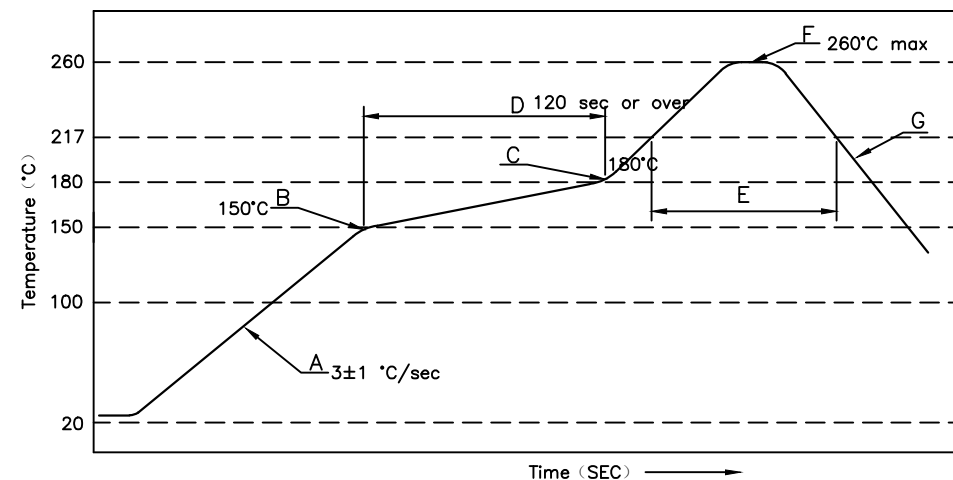


5. TEMPERATURE CONDITION OF REFLOW SOLDERING:

Contents	Soldering Condition
A: Increasing speed	3±1 °C/sec
B: Pre-heat starting speed	150°C
C: Pre-heat ending speed	180°C
D: Pre-heat interval	120 sec or over
E: Over 217°C time	60~150 sec
F: Peak Temperature(Tp)	260°C max
Time within 5°C of actual Peak Temp(Tp)	10 sec max
G: Ramp down rate	6°C/sec max

Note:

Type of lead-free solder should be 96.5Sn-3.0Ag-0.5Cu or 99.3Sn-0.7Cu.



QUALITY SYMBOLS MAJOR CRITICAL	DRAWN BY: DENG JIANXIANG '180516 DATE:	
	CHECKED BY: TENG CHANG HO '180516 DATE:	
GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±XXX .X ±0.38 .XX ±0.20 .XXX ±XXX ANGLES ±1°	APPROVED BY: KUO JUNG HSUN '180516 DATE:	TITLE RJ45 1000BASE-T,TAB UP, W/O LED
	UNITS: mm SCALE: 1:1	 SHEET NO.: 3 OF 3